

N-channel 650V, 7A, 0.65Ω Super-Junction Power MOSFET

Description

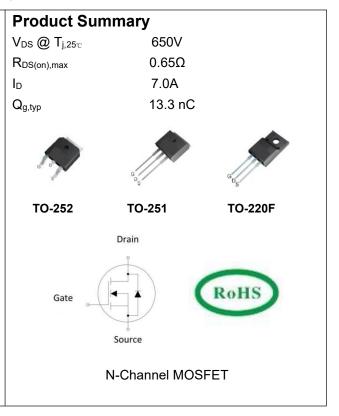
Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFET, designed according to the SJ principle. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

- Very low FOM RDS(on)×Qg
- ◆ 100% UIS tested
- RoHS compliant

Applications

- ◆ Power factor correction (PFC).
- Switched mode power supplies (SMPS).
- Uninterrupted power supply (UPS).



Marking information

Product	Package	Marking	Packing methed
RMA65R650SN	TO-252	RMA65R650SN	Reel
RMG65R650SN	TO-251	RMG65R650SN	Tube
RMC65R650SN	TO-220F	RMC65R650SN	Tube

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	650	V
Continuous drain current (T _C = 25°C)	I _D	7	А
(T _C = 100°C)		4.4	Α
Pulsed drain current 1)	I _{DM}	21	Α
Gate-Source voltage	V _{GSS}	±30	V
Avalanche energy, single pulse 2)	Eas	120	mJ
Avalanche current, repetitive 3)	I _{AR}	1.2	А
Power Dissipation TO-252 /TO-251 ($T_C = 25^{\circ}C$)	D	63	W
- Derate above 25°C	P _D	0.5	W/°C
Power Dissipation TO-220F (T _C = 25°C)	D.	32	W
- Derate above 25°C	P _D	0.26	W/°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C
Continuous diode forward current	Is	7	А



RMA65R650SN/RMG65R650SN/RMC65R650SN

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Diode pulse current	I _{S,pulse}	21	Α

Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO252/TO-251	TO-220F	
Thermal Resistance, Junction-to-Case	Rejc	2	4	°C/W
Thermal Resistance, Junction-to-Ambient	R _{0JA}	62	68	°C/W
Soldering temperature, wave soldering only allowed	т	260	260	°C
at leads. (1.6mm from case for 10s)	I sold	200	200	

Electrical Characteristics T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics			·			
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	650	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	2.5		4.0	V
Drain cut-off current	I _{DSS}	V _{DS} =650 V, V _{GS} =0 V,				μA
		T _j = 25°C	-	-	1	
		T _j = 125°C	-	10		
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =3.5 A	-			
		T _j = 25°C	-	0.56	0.65	Ω
			-			
Dynamic characteristics			·			
Input capacitance	Ciss	V _{DS} = 100 V, V _{GS} = 0 V,	-	493	-	
Output capacitance	Coss	f = 1MHz	-	32	-	pF
Reverse transfer capacitance	C _{rss}		-	1.6	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 400V, I _D = 3.5A	-	11.6	-	
Rise time	t _r	$R_G = 25\Omega$, $V_{GS}=10V$	-	23	-	ns
Turn-off delay time	t _{d(off)}]	-	53	-	
Fall time	t _f]	-	35.8	-	
Gate charge characteristics	<u>'</u>		'	1		1
Gate to source charge	Q _{gs}	V _{DD} =520 V, I _D =3.5A,	-	2.8	-	
Gate to drain charge	Q _{gd}	V _{GS} =0 to 10 V	-	4.7	-	nC
Gate charge total	Qg		-	13.3	-	
Gate plateau voltage	V _{plateau}		-	5.5	-	V
Reverse diode characteristics	'		'			
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =3.5A	-	0.85	-	V
Reverse recovery time	t _{rr}	V _R =50 V, I _F =3.5A,	-	201.4	-	ns
Reverse recovery charge	Qrr	dl _F /dt=100 A/µs	-	1.3	-	μC
Peak reverse recovery current	I _{rrm}	1	-	11.5	-	Α



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Notes:

1. Limited by maximum junction temperature, maximum duty cycle is 0.75.

2. I_{AS} = 2A, V_{DD} = 50V, Starting T_j = 25°C.



Electrical Characteristics Diagrams

Figure 1. Output Characteristics 20 20V 10V 87 Drain current l_D (A) **7V** 6V 5.5V 5V 4.5V 5 0 5 10 15 20 Drain-source voltage V_{DS} (V)

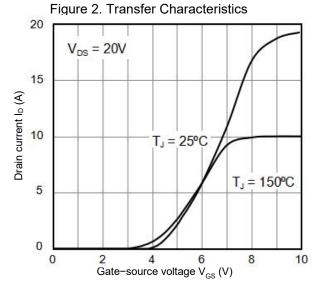


Figure 3. On-Resistance vs. Drain Current

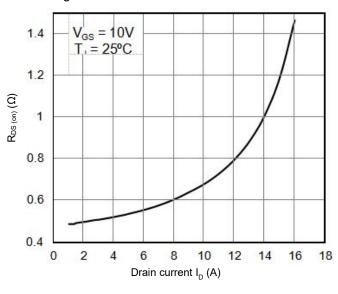


Figure 4. Capacitance Characteristics

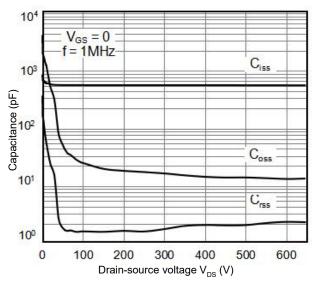


Figure 5. Gate Charge Characteristics

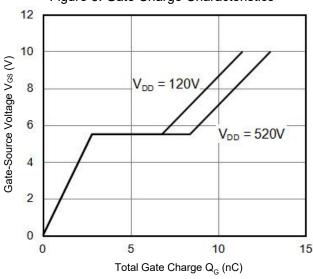
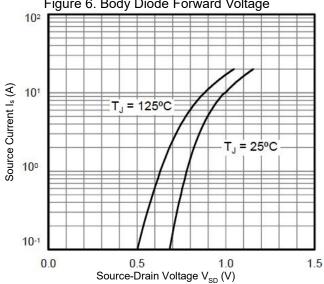


Figure 6. Body Diode Forward Voltage



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Figure 7. Breakdown Voltage vs. Temperature

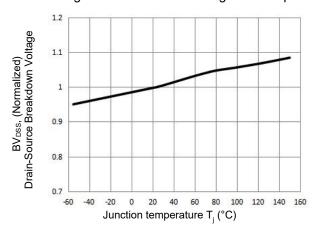
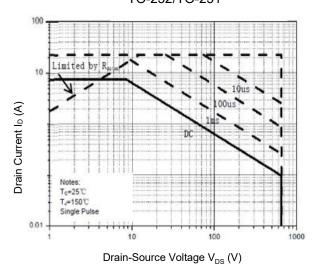


Figure 9. Maximum Safe Operating Area TO-252/TO-251



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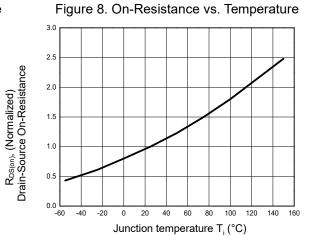
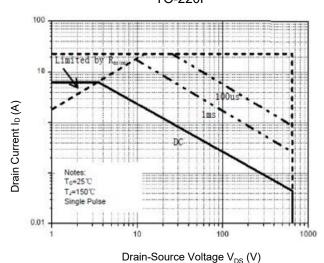


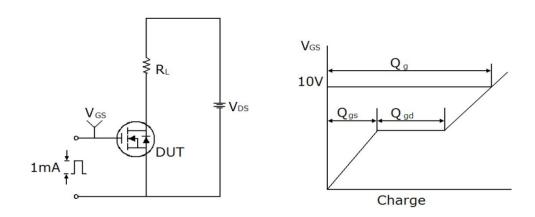
Figure 10. Maximum Safe Operating Area TO-220F



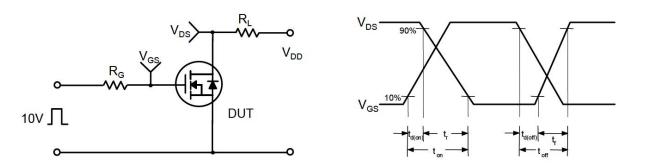


Test Circuits

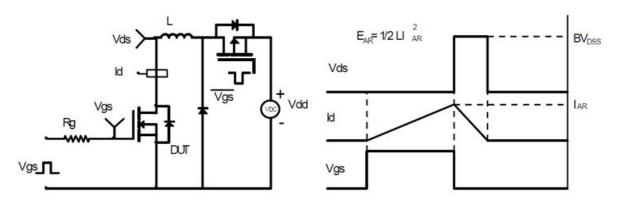
Gate Charge Test Circuit & Waveform



Switching Test Circuit & Waveform

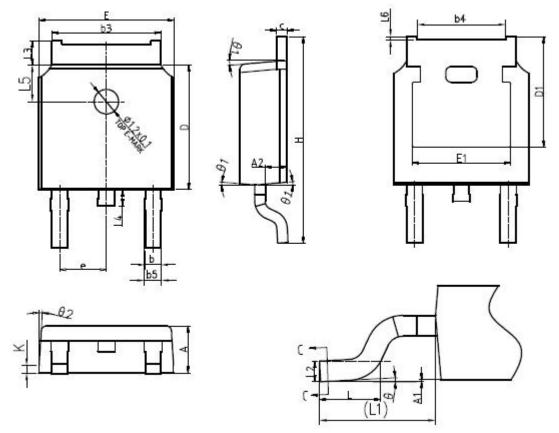


Unclamped Inductive Switching Test Circuit & Waveform





Mechanical Dimensions for TO-252



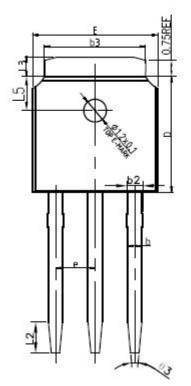
单位: mm

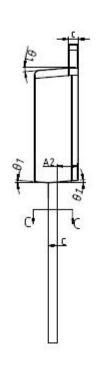
		mm				
SYMBOL	MIN	NOM	MAX			
*A	2.20	2. 30	2. 38			
*A1	0.00	(5)	0.10			
A2	0.97	1.07	1. 17			
*b	0.72	0.78	0.85			
b1	0.71	0.76	0.81			
*b3	5. 23	5. 33	5. 46			
b4	4.27	4.32	4. 37			
b5	0.72	0.88	0. 93			
*c	0.47	0. 53	0.58			
c1	0.46	0. 51	0.56			
*D	6.00	6. 10	6. 20			
D1		5. 30REF				

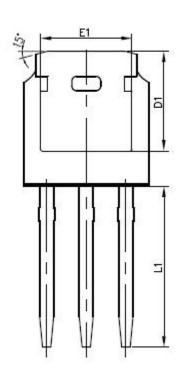
*E	6.50	6.60	6.70			
E1	4.70	4.83	4.92			
*e		2. 286BSC				
L	1.40	1.50	1.70			
L1	Î	2. 90REF				
L2		0. 51BSC				
*L3	0.90	-	1.25			
*L4	0.60	0.80	1.00			
L5	1.70	1.80	1.90			
L6	0	0.047	0.123			
θ	0°		8°			
* 01	5°	7°	9°			
0.2	5°	7°	9°			
K	0. 40REF					



Mechanical Dimensions for TO-251



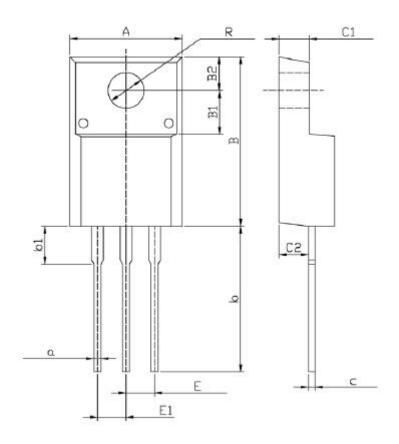




CVMDOL		MM		
SYMBOL	MIN	NOM	MAX	
*A	2. 20	2.30	2.38	
*A2	0.97	1.07	1. 17	
*b	0.72	0.78	0.85	
b1	0.71	0.76	0.81	
*b2	0.72	0.88	0.95	
*b3	5. 23	5. 33	5.46	
*c	0.47	0.53	0.58	
c1	0.46	0.51	0.56	
*D	6.00	6.10	6. 20	
D1	o sellenter i	5. 30REF		
*E	6. 50	6.60	6.70	
E1	4.70	4.83	4.92	
*e	5	2. 286BSC		
*L1	9. 20	9.40	9.60	
L2	1. 25	1.35	1.45	
*L3	0.90	1.02	1. 25	
L5	1.70	1.80	1.90	
*01	5°	7°	9°	
02	5°	7°	9°	
03	11°	13°	15°	
K	0. 40REF			



Mechanical Dimensions for TO-220F



Symbol Dimensions In Millimeters			Dimensions In Millineters		
Symbol	Min	Max	Symbol	Min	Max
С	4.3	4.7	b1	2.9	3.9
Α	9.7	10.3	a	0.55	0.75
В	14.7	15.3	E	2.29	2.79
B1	3.8	4.0	E1	2.29	2.79
B2	2,9	3.1	C1	2.5	2.9
R	3.0	3.4	CS	2.5	2.7
b	12.5	13.5	С	0.5	0.7